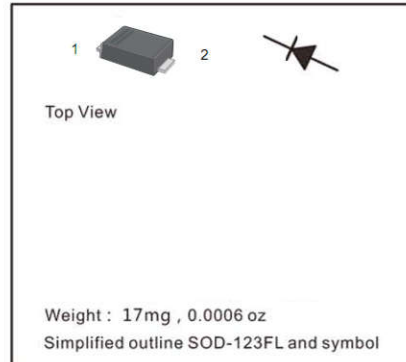


Surface Mount Schottky Barrier Rectifier
 Reverse Voltage - 20 to 200 V
 Forward Current - 1.0 A

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



● Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

● Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SK12WA	SK14WA	SK16WA	SK18WA	SK110WA	SK112WA	SK115WA	SK120WA	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	80	100	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	40				25				A
Max Instantaneous Forward Voltage at 1 A	V_F	0.55	0.70		0.85		0.90		V	
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Reverse Voltage $T_a = 100^\circ\text{C}$	I_R	0.3			0.2		0.1		mA	
		10			5		2			
Typical Junction Capacitance ¹⁾	C_j	110	80							pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	115								°C/W
Operating Junction Temperature Range	T_j	-55 ~ +125								°C
Storage Temperature Range	T_{stg}	-55 ~ +150								°C

1) Measured at 1MHz and applied reverse voltage of 4 V D.C.

2) P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.

Fig.1 Forward Current Derating Curve

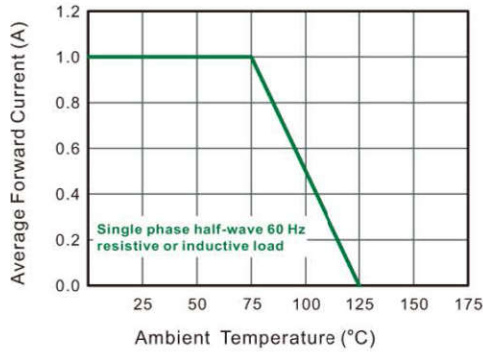


Fig.2 Typical Reverse Characteristics

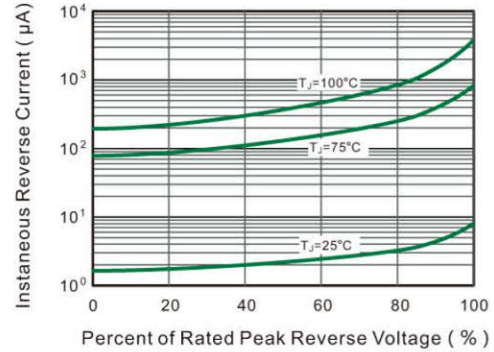


Fig.3 Typical Forward Characteristic

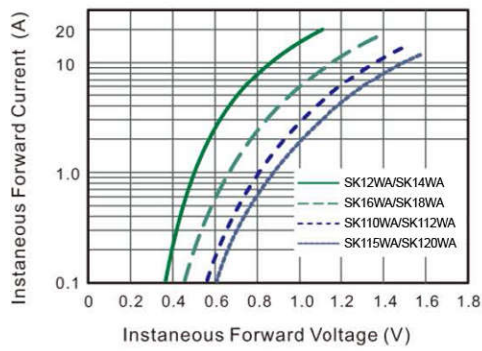


Fig.4 Typical Junction Capacitance

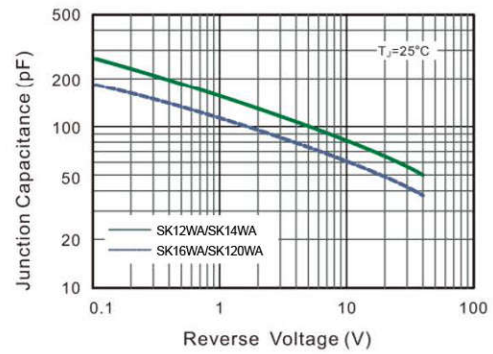


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

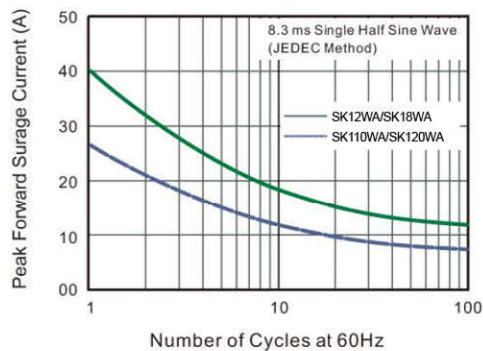
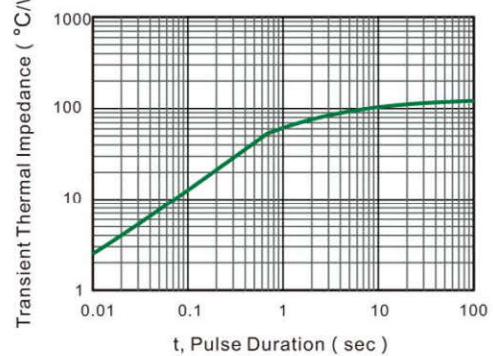


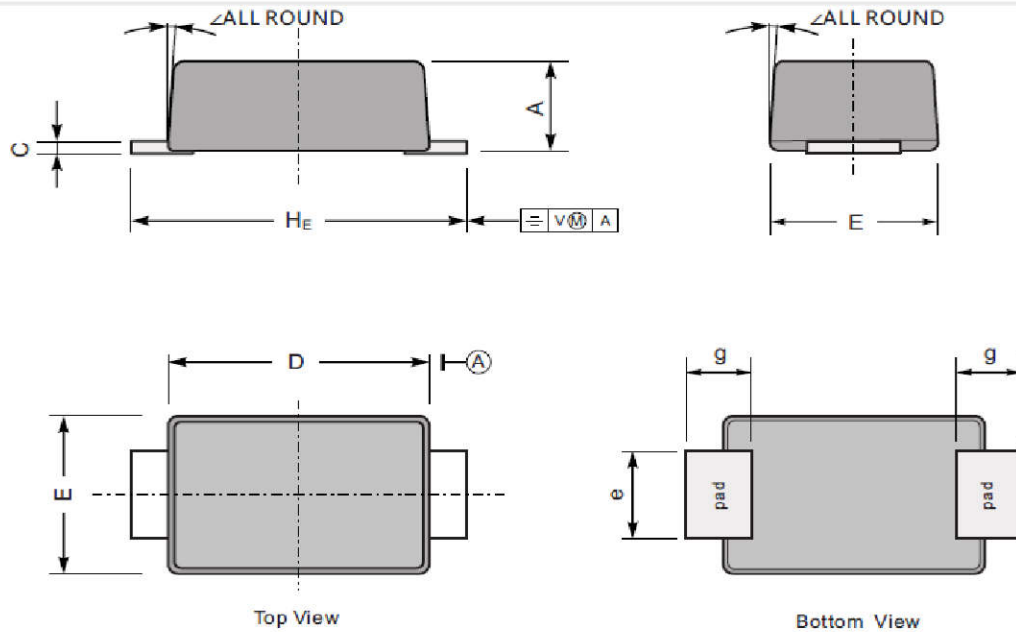
Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE

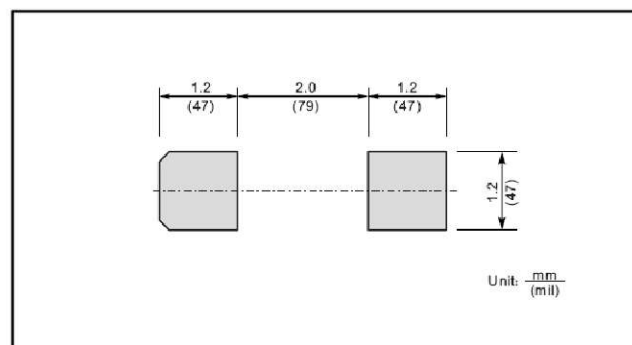
Plastic surface mounted package; 2 leads

S0D1237L

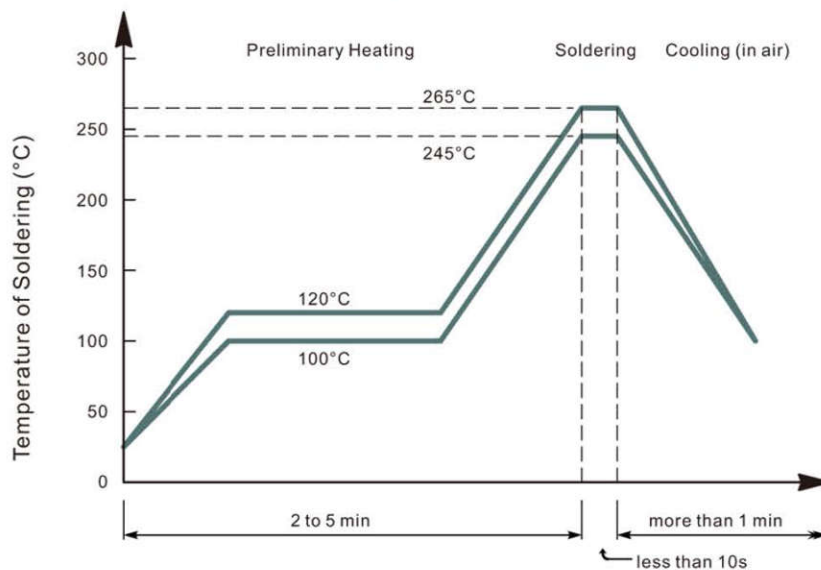


UNIT		A	C	D	E	e	g	H _E	\angle
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

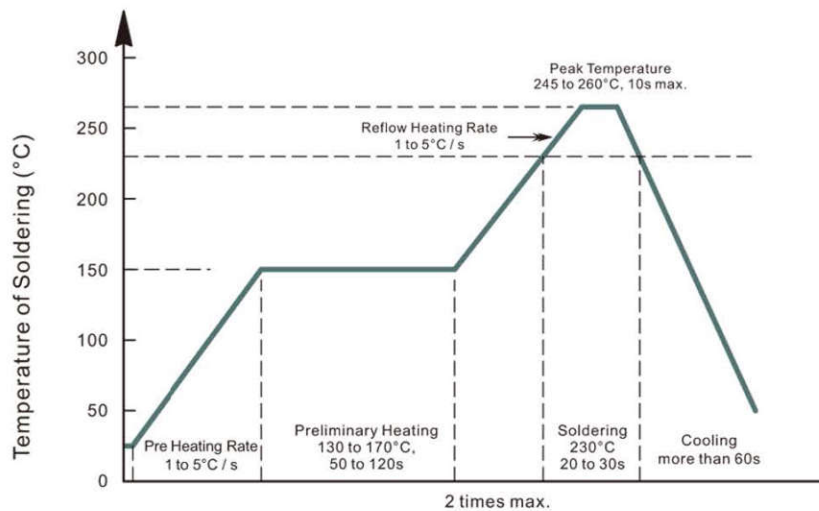
The recommended mounting pad size



• Recommended condition of flow soldering



• Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)

• Condition of hand soldering

Temperature: 320°C

Time: 3s max.

Times: one time

• Remark:

Lead free solder paste (96.5Sn/3.0Ag/0.5Cu)

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [Schottky Diodes & Rectifiers](#) category:

Click to view products by [Shikues](#) manufacturer:

Other Similar products are found below :

[MA4E2039](#) [MA4E2508M-1112](#) [MBR10100CT-BP](#) [MBR1545CT](#) [MMBD301M3T5G](#) [GS1JE-TP](#) [RB160M-50TR](#) [BAS 3010S-02LRH E6327](#)
[BAT 54-02LRH E6327](#) [NSR05F40QNXT5G](#) [NSVR05F40NXT5G](#) [NTE555](#) [JANS1N6640](#) [SB07-03C-TB-H](#) [SBS818-TL-E](#) [SK310-T](#)
[SK33A-TP](#) [SK34B-TP](#) [SS3003CH-TL-E](#) [PDS3100Q-7](#) [GA01SHT18](#) [CRS10I30A\(TE85L,QM](#) [MA4E2501L-1290](#) [MBRB30H30CT-1G](#)
[DMJ3940-000](#) [SB007-03C-TB-E](#) [SK32A-TP](#) [SK33B-TP](#) [SK35A-TP](#) [SK38B-LTP](#) [SK38B-TP](#) [NRVBM120LT1G](#) [NTE505](#)
[NTSB30U100CT-1G](#) [SS0503SH-TL-E](#) [VS-6CWQ10FNHM3](#) [CRG04\(T5L,TEMQ\)](#) [ACDBA1100LR-HF](#) [ACDBA1200-HF](#) [ACDBA2100-HF](#)
[ACDBA240-HF](#) [ACDBA3100-HF](#) [CDBQC0530L-HF](#) [ACDBA260LR-HF](#) [ACDBA1100-HF](#) [MA4E2502L-1246](#) [10BQ060-M3/5BT](#)
[NRVB130LSFT1G](#) [CRS08TE85LQM](#) [PMAD1108-LF](#)